

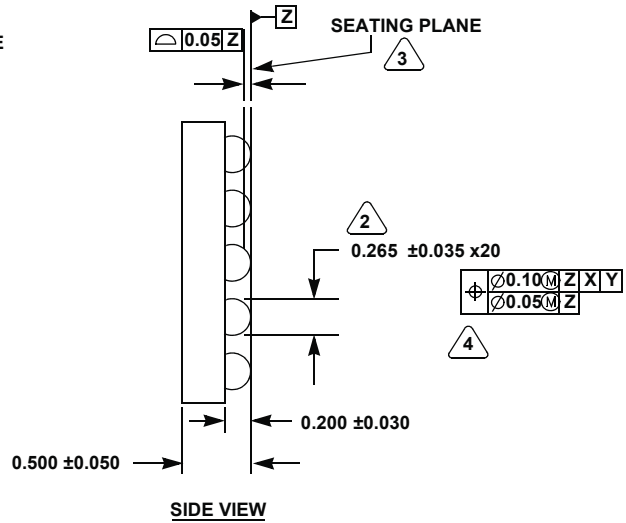
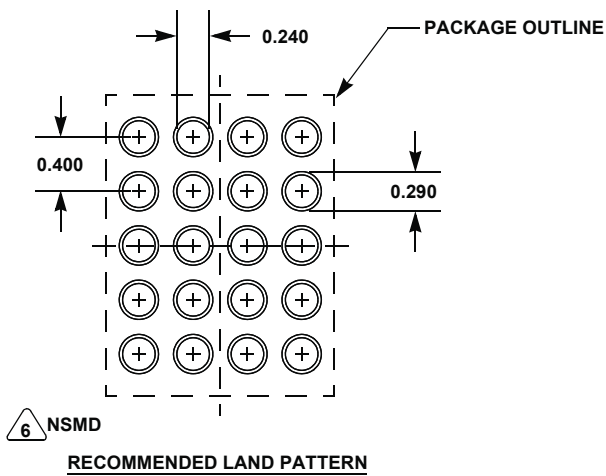
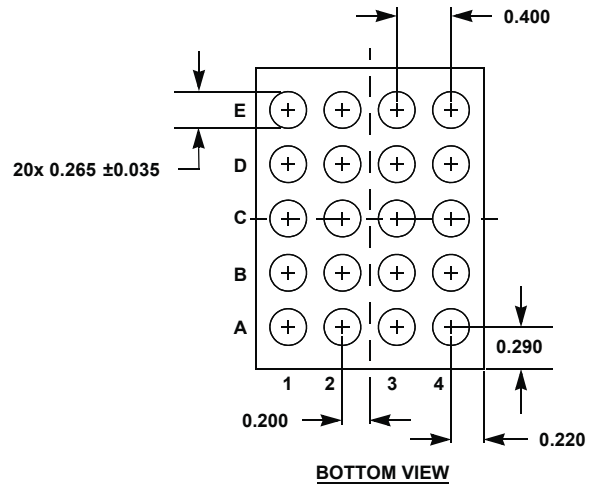
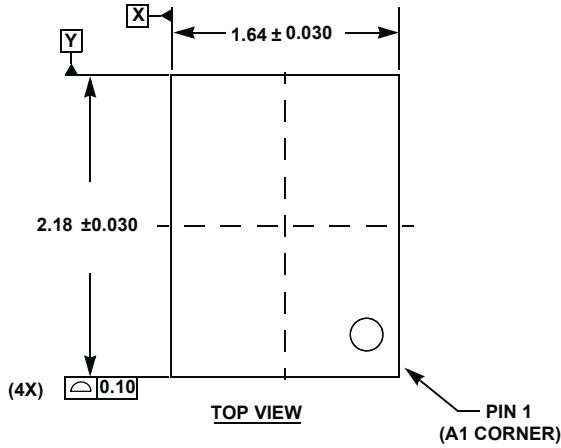
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

### W4x5.20J

20 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm Pitch)

Rev 1, 1/15



#### NOTES:

- Dimensions and tolerance per ASMEY 14.5 - 1994.
- Dimension is measured at the maximum bump diameter parallel to primary datum Z.
- Primary datum Z and seating plane are defined by the spherical crowns of the bump.
- Bump position designation per JESD 95-1, SPP-010.
- All dimensions are in millimeters.
- NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).